

S/N 09/483,881



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Kie Y. AHN ET AL.  
Serial No.: 09/483,881  
Filed: January 18, 2000  
Title: SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

Examiner: Group Art Unit 1752, 1751  
Docket: 303.672/JS1

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**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants further request that a copy of the 1449 form, initialled by the Examiner to indicate that all listed citations have been considered, be returned with the next official communication.

Under 37 C.F.R. § 1.97(b)(3), it is believed that no fee or certificate is required with this Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge any additional fees or credit any overpayment to Account No. 19-0743.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

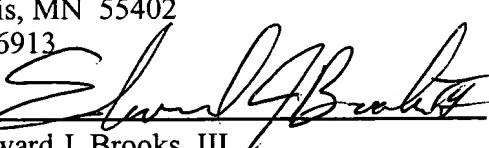
KIE Y. AHN ET AL.

By their Representatives,

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Date 7/12/2001

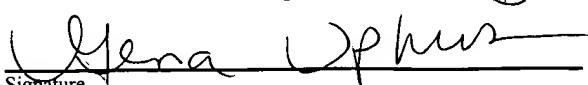
By

  
Edward J. Brooks, III  
Reg. No. 40,925

**CERTIFICATE UNDER 37 CFR 1.8:** The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 13 day of July, 2001.

Gina M. Uphus

Name

  
Signature